Title (en)
PACKAGED ELECTRONIC MODULE AND MANUFACTURING METHOD THEREOF

Title (de)
VERPACKTES ELEKTRONISCHES MODUL UND DESSEN HERSTELLUNGSVERFAHREN

Title (fr)
MODULE ÉLECTRONIQUE MIS SOUS BOÎTIER ET SON PROCÉDÉ DE FABRICATION

Publication
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Application
EP 20885861 A 20200311

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Abstract (en)
[origin: WO2021091587A2] The present invention is a packaged electronic module with embedded electronics for use in smart cards. This invention assembles a plurality of electronics components on a flexible printed circuit, together with an integrated circuit chip and a contact plate, into a module. This module can then be embedded into a plastic card, using regular milling techniques, by a card manufacturer. This method packages the plurality of electronics components into a module. The present invention provides a business with the capability to avoid additional capital expenditure required for special equipment and enables all existing card manufacturers to manufacture smart cards with embedded electronics.

IPC 8 full level
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Citation (search report)
• [XI] EP 2426627 A1 20120307 - OBERTHUR TECHNOLOGIES [FR]
• [AD] US 2019012588 A1 20190110 - LALO CYRIL [US], et al
• [A] DE 10221214 A1 20031127 - ORGA KARTENSYSTEME GMBH [DE]
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